

**PHOTOCOUPLER**  
**PS2501A-1, PS2501AL-1****HIGH ISOLATION VOLTAGE  
SINGLE TRANSISTOR TYPE  
MULTI PHOTOCOUPLER SERIES**

–NEPOC Series–

**DESCRIPTION**

The PS2501A-1 and PS2501AL-1 are optically coupled isolators containing a GaAs light emitting diode and an NPN silicon phototransistor.

The PS2501A-1 is in a plastic DIP (Dual In-line Package) and the PS2501AL-1 are lead bending type (Gull-wing) for surface mount.

**FEATURES**

- High isolation voltage ( $BV = 5\,000\text{ V r.m.s.}$ )
- Ordering number of taping product: PS2501AL-1-E3, E4, F3, F4
- Safety standards
  - UL approved: File No. E72422

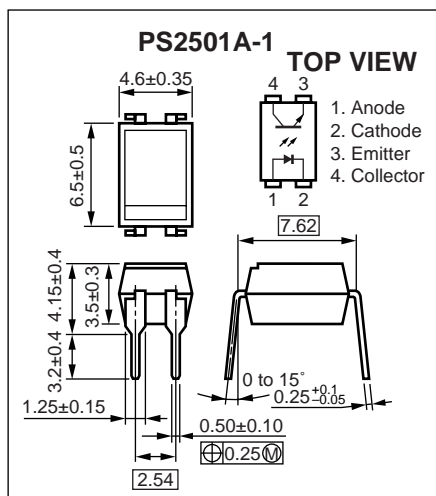
**APPLICATIONS**

- Power supply
- Telephone/FAX.
- FA/OA equipment
- Programmable logic controller

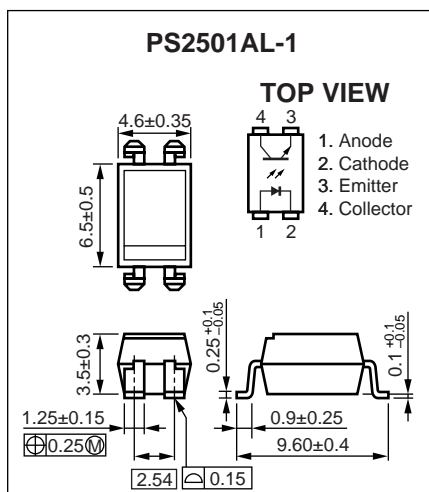
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PACKAGE DIMENSIONS (UNIT : mm)

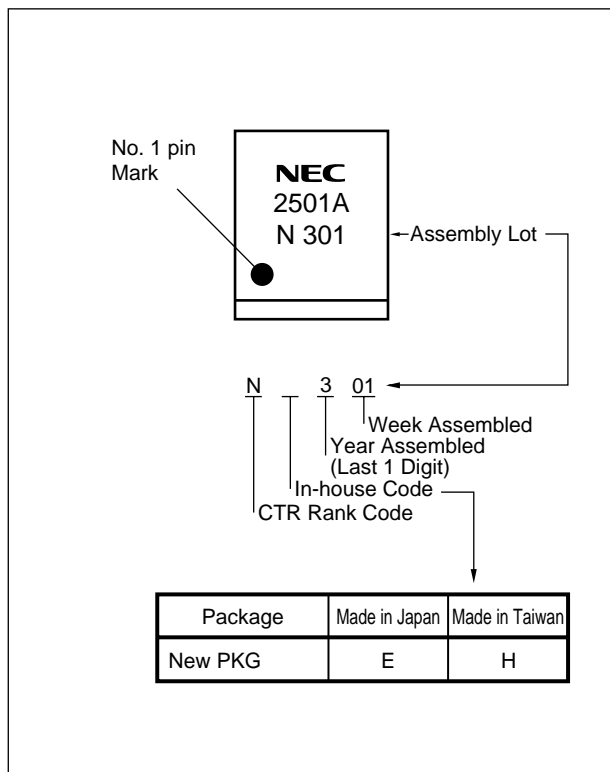
DIP Type



Lead Bending Type



## MARKING EXAMPLE



## ORDERING INFORMATION

Part Number	Package	Packing Style	Safety Standard Approval	Application Part Number <sup>*1</sup>
PS2501A-1	4-pin DIP	Magazine case 100 pcs	Standard products (UL Approved)	PS2501A-1
PS2501AL-1				
PS2501AL-1-E3		Embossed Tape 1 000 pcs/reel		
PS2501AL-1-E4				
PS2501AL-1-F3		Embossed Tape 2 000 pcs/reel		
PS2501AL-1-F4				

\*1 For the application of the Safety Standard, following part number should be used.

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise specified)**

Parameter		Symbol	Ratings	Unit
Diode	Reverse Voltage	V <sub>R</sub>	6	V
	Forward Current (DC)	I <sub>F</sub>	30	mA
	Power Dissipation Derating	ΔP <sub>D</sub> /°C	1.5	mW/°C
	Power Dissipation	P <sub>D</sub>	150	mW
	Peak Forward Current <sup>*1</sup>	I <sub>FP</sub>	0.5	A
Transistor	Collector to Emitter Voltage	V <sub>CEO</sub>	70	V
	Emitter to Collector Voltage	V <sub>ECO</sub>	5	V
	Collector Current	I <sub>C</sub>	30	mA
	Power Dissipation Delay	ΔP <sub>C</sub> /°C	1.5	mW/°C
	Power Dissipation	P <sub>C</sub>	150	mW
Isolation Voltage <sup>*2</sup>		BV	5 000	Vr.m.s.
Operating Ambient Temperature		T <sub>A</sub>	−55 to +100	°C
Storage Temperature		T <sub>stg</sub>	−55 to +150	°C

\*1 PW = 100 μs, Duty Cycle = 1%

\*2 AC voltage for 1 minute at T<sub>A</sub> = 25°C, RH = 60% between input and output

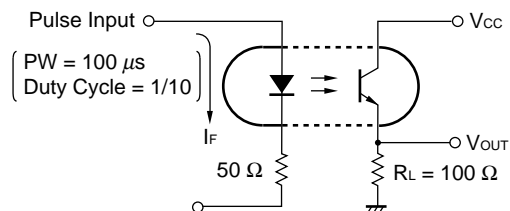
**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)**

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 10 mA		1.2	1.4	V
	Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 5 V			5	μA
	Terminal Capacitance	C <sub>t</sub>	V = 0 V, f = 1.0 MHz		10		pF
Transistor	Collector to Emitter Dark Current	I <sub>CEO</sub>	V <sub>CE</sub> = 70 V, I <sub>F</sub> = 0 mA			100	nA
Coupled	Current Transfer Ratio (I <sub>C</sub> /I <sub>F</sub> ) <sup>*1</sup>	CTR	I <sub>F</sub> = 5 mA, V <sub>CE</sub> = 5 V	50		400	%
	Collector Saturation Voltage	V <sub>CE(sat)</sub>	I <sub>F</sub> = 10 mA, I <sub>C</sub> = 2 mA		0.13	0.3	V
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1.0 kV <sub>DC</sub>	10 <sup>11</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1.0 MHz		0.4		pF
	Rise Time <sup>*2</sup>	t <sub>r</sub>	V <sub>CC</sub> = 10 V, I <sub>C</sub> = 2 mA, R <sub>L</sub> = 100 Ω		5		μs
	Fall Time <sup>*2</sup>	t <sub>f</sub>			7		

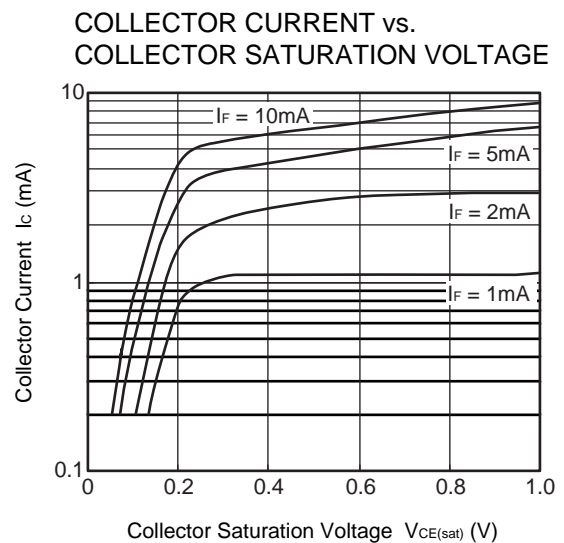
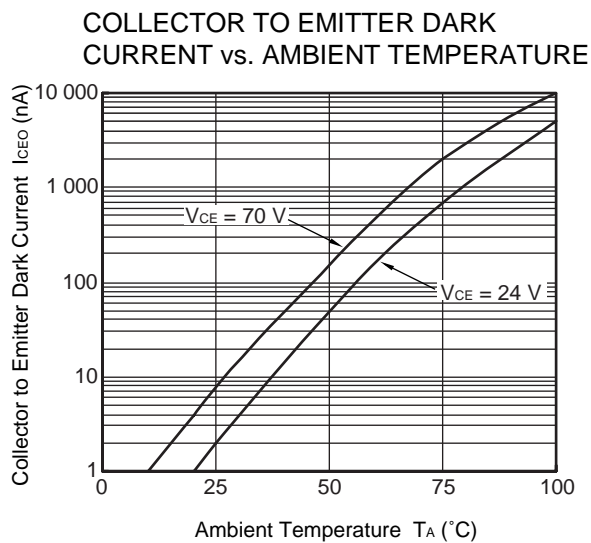
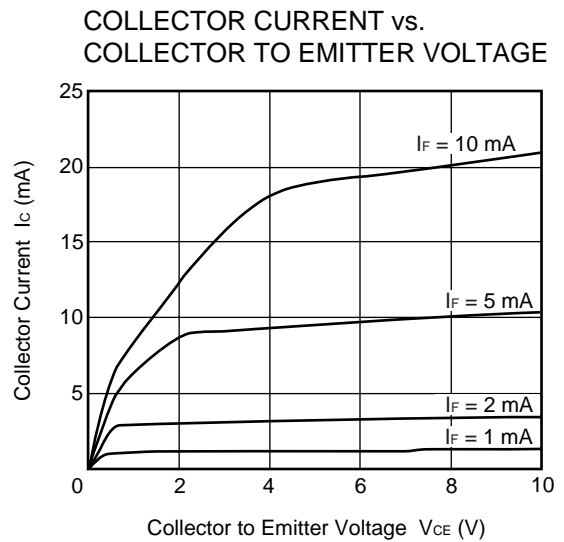
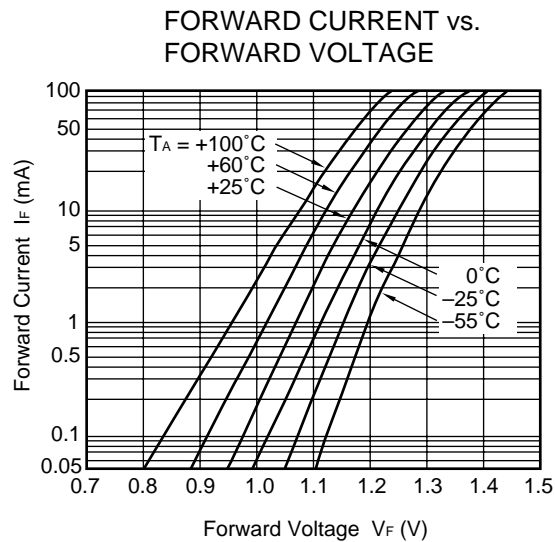
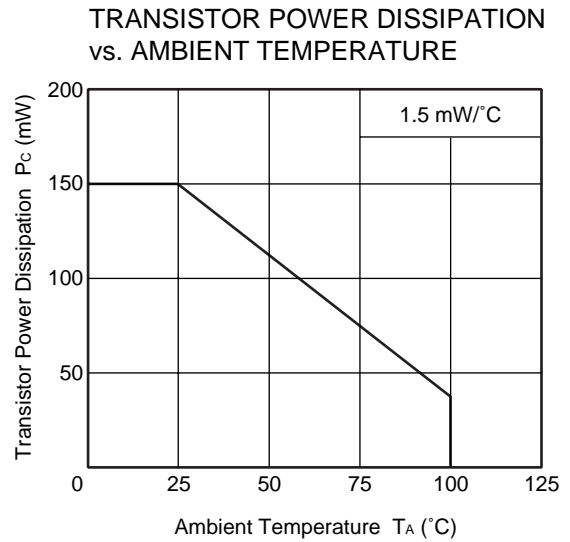
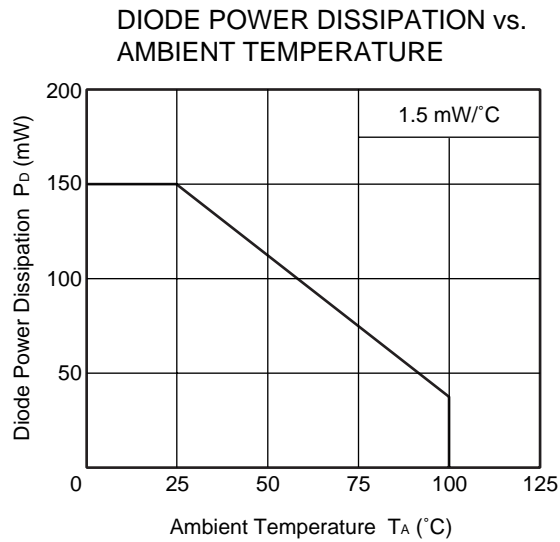
**\*1 CTR rank**

- N : 50 to 400 (%)
- H : 80 to 160 (%)
- W : 130 to 260 (%)
- Q : 100 to 200 (%)
- L : 200 to 400 (%)

**\*2 Test circuit for switching time**

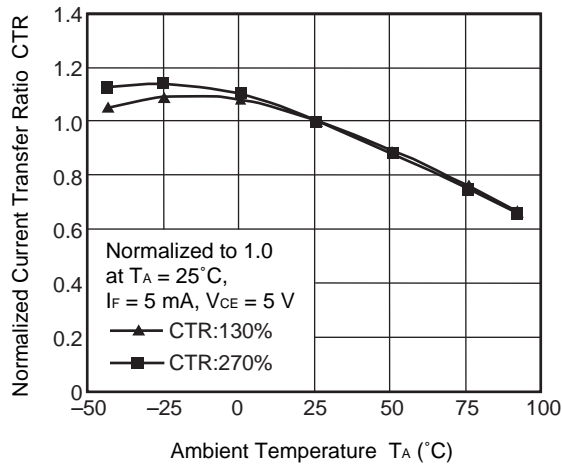


**TYPICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)**

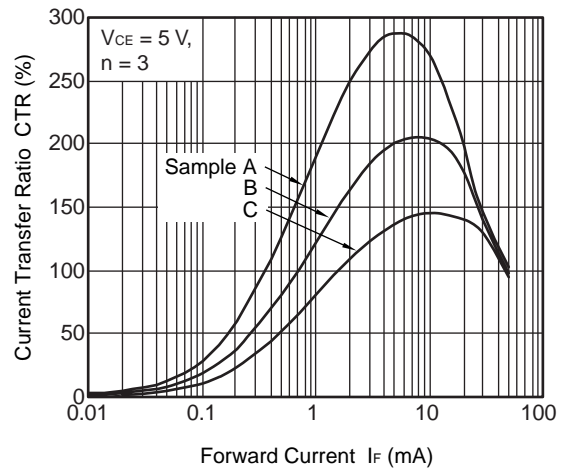


**Remark** The graphs indicate nominal characteristics.

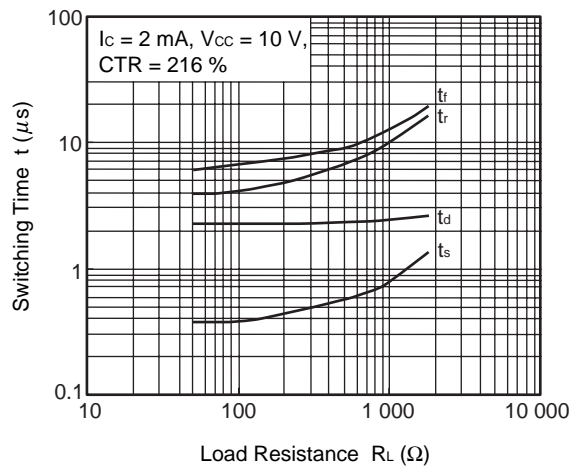
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



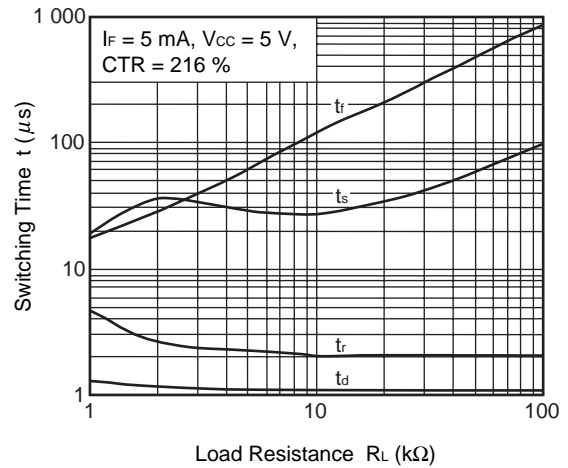
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



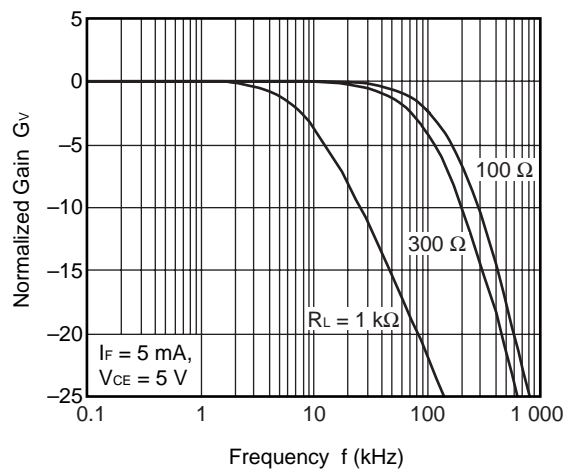
SWITCHING TIME vs. LOAD RESISTANCE



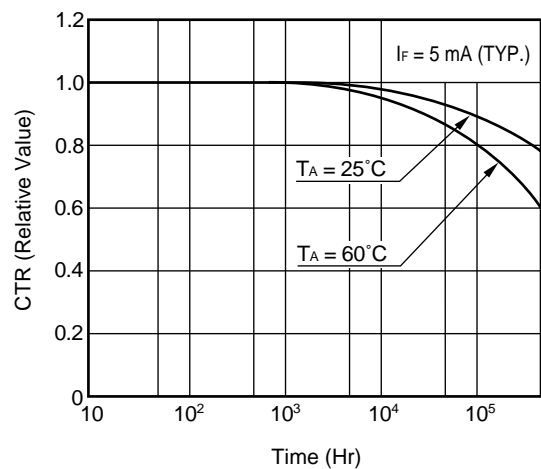
SWITCHING TIME vs. LOAD RESISTANCE



FREQUENCY RESPONSE



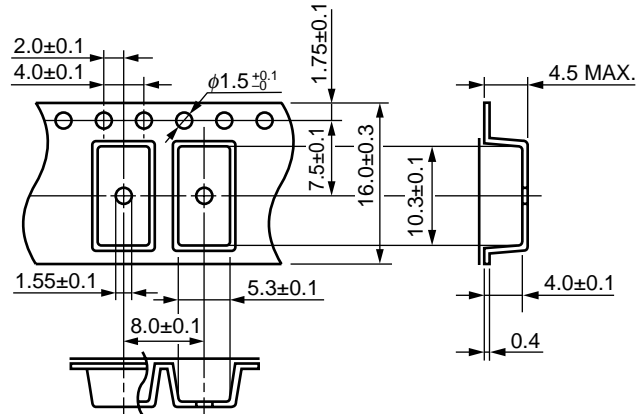
LONG TERM CTR DEGRADATION



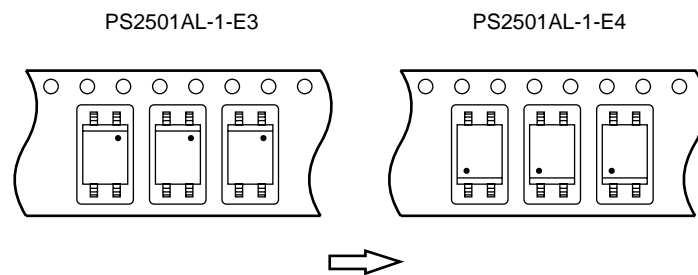
**Remark** The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT : mm)

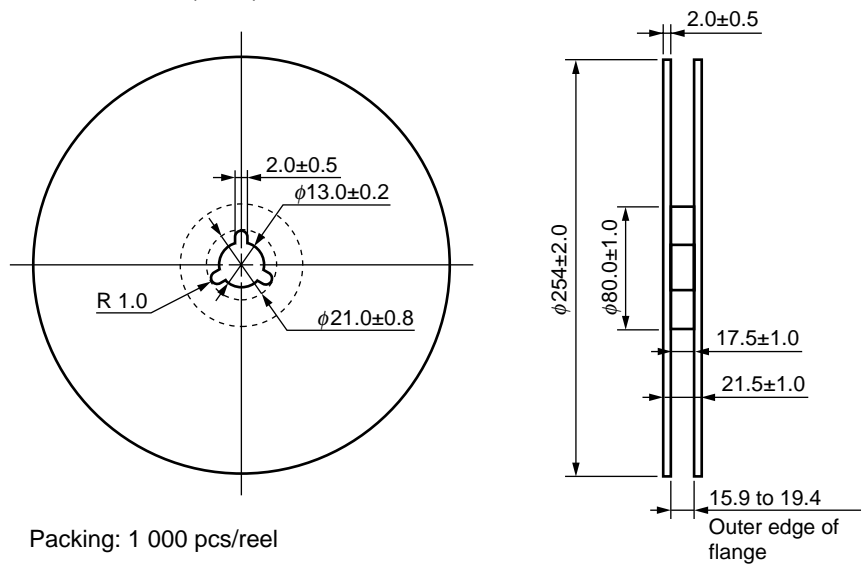
Outline and Dimensions (Tape)



Tape Direction

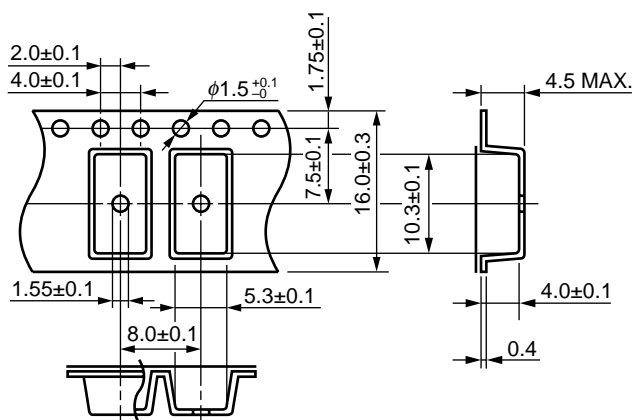


Outline and Dimensions (Reel)

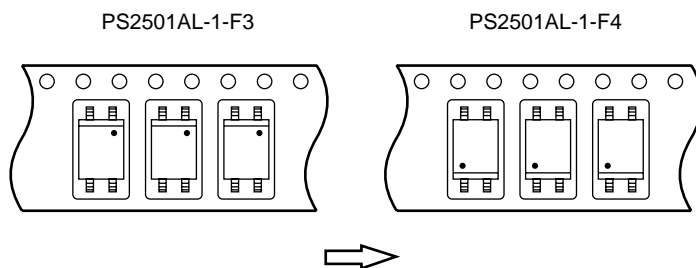




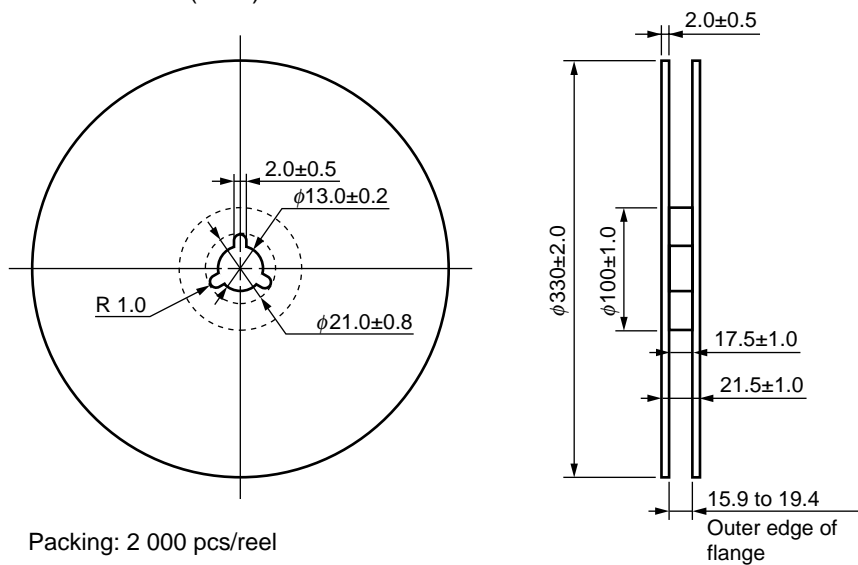
### Outline and Dimensions (Tape)



### Tape Direction



### Outline and Dimensions (Reel)

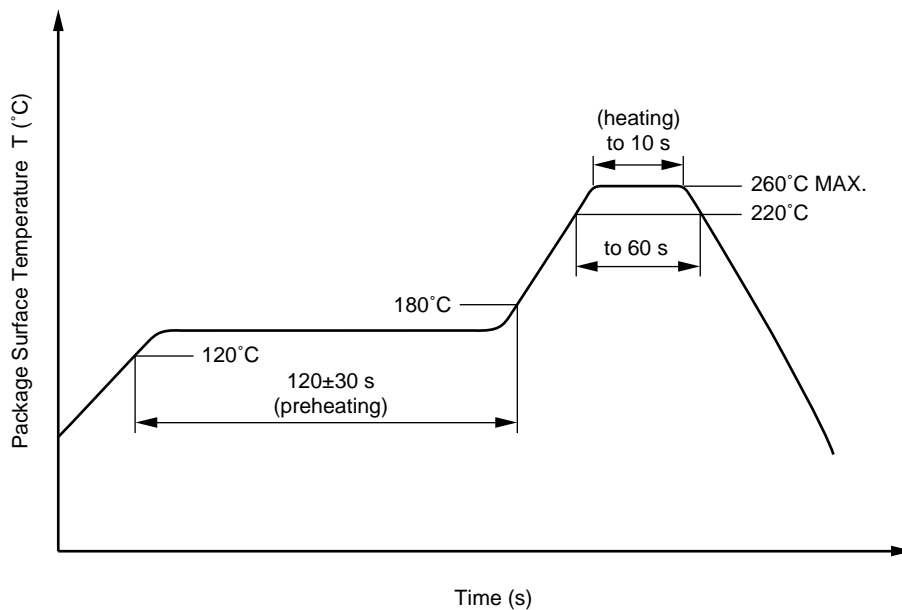


## NOTES ON HANDLING

### (1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



### (2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

### (3) Cautions

- Fluxes  
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

## USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

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M8E 00.4-0110

<b>Caution</b>	GaAs Products	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"> <li>• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.</li> </ul> <ol style="list-style-type: none"> <li>1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li> <li>2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li> </ol> <ul style="list-style-type: none"> <li>• Do not burn, destroy, cut, crush, or chemically dissolve the product.</li> <li>• Do not lick the product or in any way allow it to enter the mouth.</li> </ul>
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► For further information, please contact

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